NEC

MOS INTEGRATED CIRCUIT

μPD3798

5348 PIXELS × 3 COLOR CCD LINEAR IMAGE SENSOR

The μPD3798 is a color CCD (Charge Coupled Device) linear image sensor which changes optical images to electrical signal and has the function of color separation.

The μPD3798 has 3 rows of 5348 pixels, and each row has a single-sided readout type of charge transfer register. And it has reset feed-through level clamp circuits and voltage amplifiers. Therefore, it is suitable for 600 dpi/A4 color image scanners, color facsimiles and so on.

FEATURES

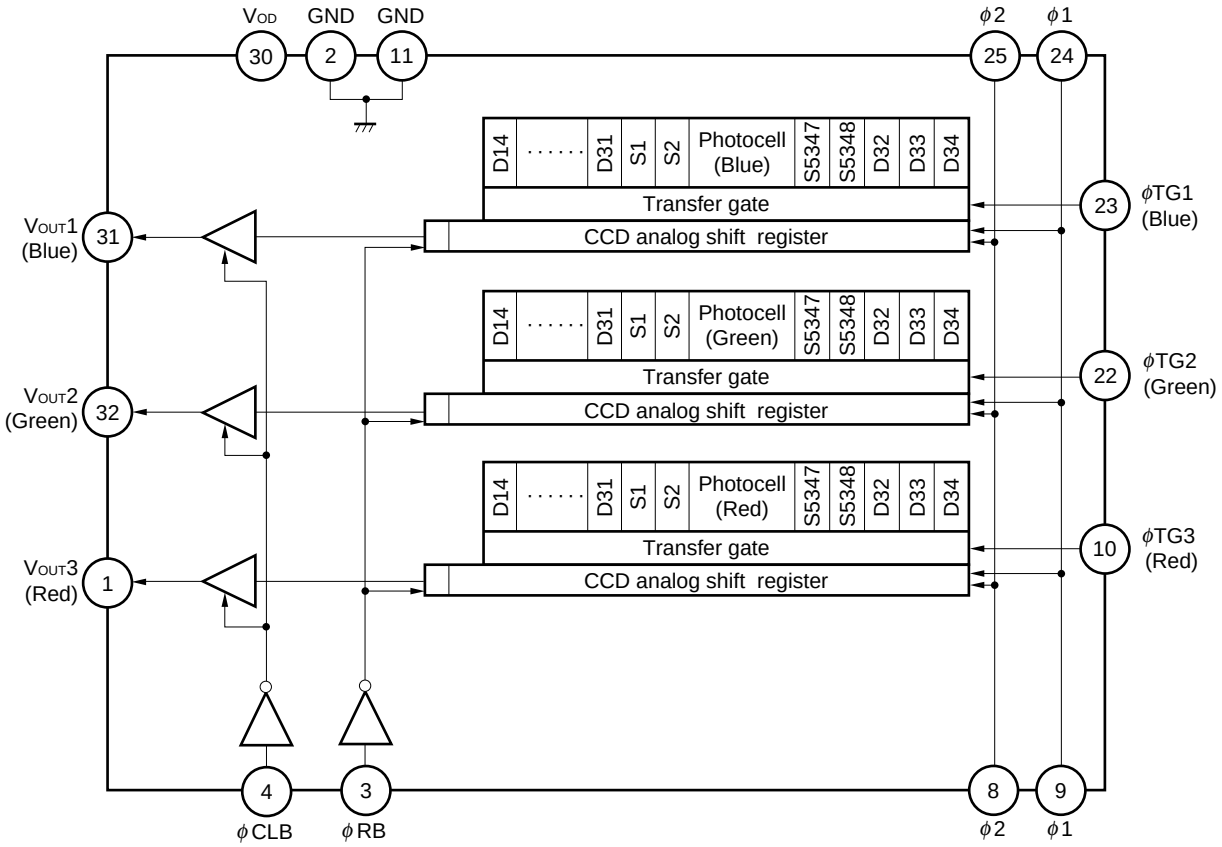
- Valid photocell : 5348 pixels × 3
- Photocell's pitch : 7 μm
- Line spacing : 28 μm (4 lines) Red line-Green line, Green line-Blue line
- Color filter : Primary colors (red, green and blue), pigment filter (with light resistance 10^7 lx•hour)
- Resolution : 24 dot/mm A4 (210 × 297 mm) size (shorter side)
  600 dpi US letter (8.5" × 11") size (shorter side)
- Drive clock level : CMOS output under 5 V operation
- Data rate : 5 MHz MAX.
- Power supply : +12 V
- On-chip circuits : Reset feed-through level clamp circuits
  Voltage amplifiers

ORDERING INFORMATION

Part Number	Package
μPD3798CY	CCD linear image sensor 32-pin plastic DIP (400 mil)

Document No. S14314EJ1V0DS00 (1st edition)
Date published June 1999 N CP(K)
Printed in Japan

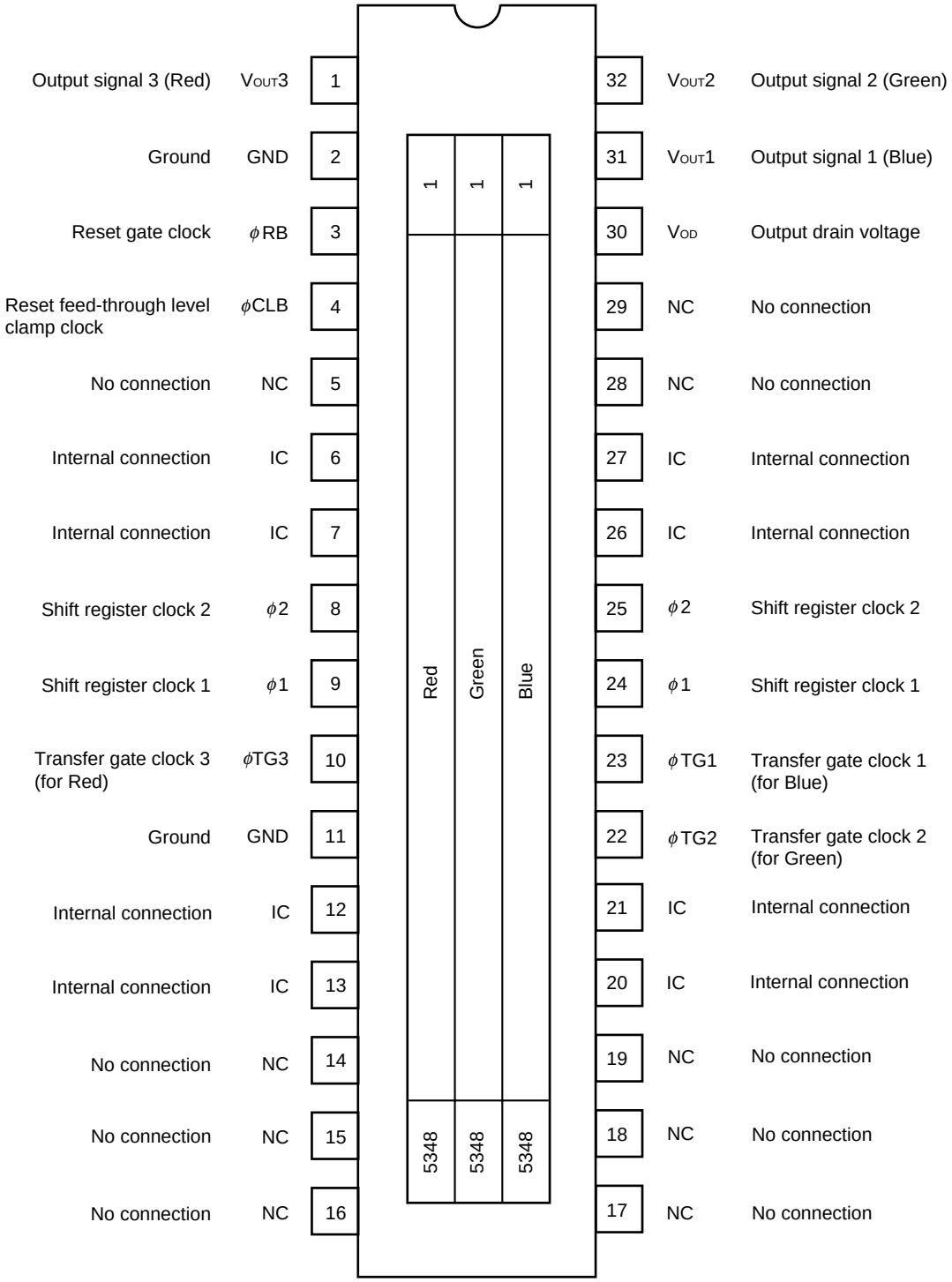
BLOCK DIAGRAM



PIN CONFIGURATION (Top View)

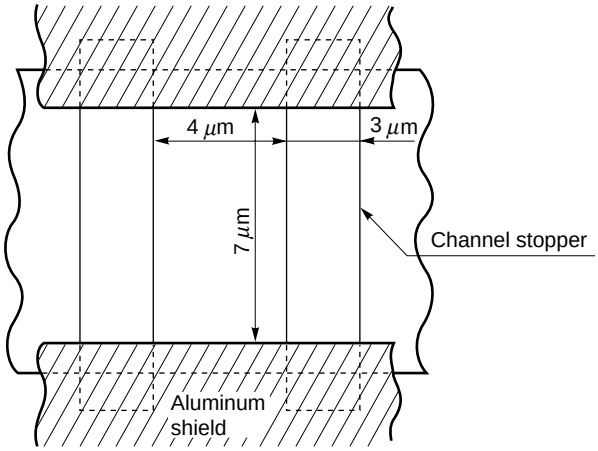
CCD linear image sensor 32-pin plastic DIP (400 mil)

- μPD3798CY

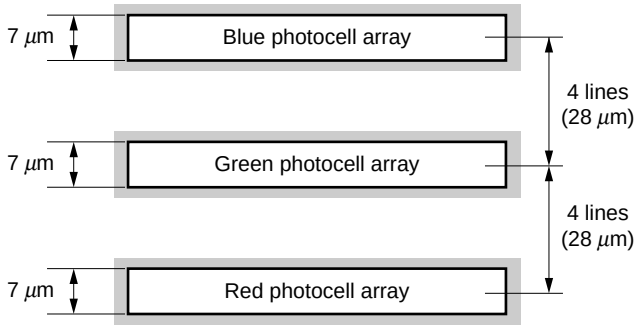


Caution Leave pins 6, 7, 12, 13, 20, 21, 26, 27 (IC) unconnected.

PHOTOCELL STRUCTURE DIAGRAM



PHOTOCELL ARRAY STRUCTURE DIAGRAM (Line spacing)



ABSOLUTE MAXIMUM RATINGS (T_A = +25 °C)

Parameter	Symbol	Ratings	Unit
Output drain voltage	V_{OD}	–0.3 to +15	V
Shift register clock voltage	$V_{\phi1}$, $V_{\phi2}$	–0.3 to +8	V
Reset gate clock voltage	$V_{\phi RB}$	–0.3 to +8	V
Reset feed-through level clamp clock voltage	$V_{\phi CLB}$	–0.3 to +8	V
Transfer gate clock voltage	$V_{\phi TG1}$ to $V_{\phi TG3}$	–0.3 to +8	V
Operating ambient temperature	T_A	–25 to +60	°C
Storage temperature	T_{stg}	–40 to +70	°C

Caution Exposure to ABSOLUTE MAXIMUM RATINGS for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The parameters apply independently.

RECOMMENDED OPERATING CONDITIONS (T_A = +25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Output drain voltage	V_{OD}	11.4	12.0	12.6	V
Shift register clock high level	$V_{\phi1H}$, $V_{\phi2H}$	4.5	5.0	5.5	V
Shift register clock low level	$V_{\phi1L}$, $V_{\phi2L}$	–0.3	0	+0.5	V
Reset gate clock high level	$V_{\phi RBH}$	4.5	5.0	5.5	V
Reset gate clock low level	$V_{\phi RBL}$	–0.3	0	+0.5	V
Reset feed-through level clamp clock high level	$V_{\phi CLBH}$	4.5	5.0	5.5	V
Reset feed-through level clamp clock low level	$V_{\phi CLBL}$	–0.3	0	+0.5	V
Transfer gate clock high level	$V_{\phi TG1H}$ to $V_{\phi TG3H}$	4.5	$V_{\phi1H}$ **Note**	$V_{\phi1H}$ **Note**	V
Transfer gate clock low level	$V_{\phi TG1L}$ to $V_{\phi TG3L}$	–0.3	0	+0.5	V
Data rate	$f_{\phi RB}$	–	1.0	5.0	MHz

Note When Transfer gate clock high level ($V_{\phi TG1H}$ to $V_{\phi TG3H}$) is higher than Shift register clock high level ($V_{\phi1H}$), Image lag can increase.

ELECTRICAL CHARACTERISTICS

(T_A = +25 °C, V_{OD} = 12 V, data rate ($f_{\phi RB}$) = 1 MHz, storage time = 5.5 ms, input signal clock = 5 V_{p-p}
light source: 3200 K halogen lamp +C-500S (infrared cut filter, t = 1mm) + HA-50 (heat absorbing filter, t = 3 mm))

Parameter		Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Saturation voltage		V_{sat}		2.0	2.5	–	V
Saturation exposure	Red	SER			0.223		lx•s
	Green	SEG			0.245		lx•s
	Blue	SEB			0.409		lx•s
Photo response non-uniformity		PRNU	V_{OUT} = 1.0 V		6	20	%
Average dark signal		ADS	Light shielding		0.2	2.0	mV
Dark signal non-uniformity		DSNU	Light shielding		1.5	3.0	mV
Power consumption		P_W			360	540	mW
Output impedance		Z_O			0.5	1	kΩ
Response	Red	R_R		7.8	11.2	14.6	V/lx•s
	Green	R_G		7.1	10.2	13.3	V/lx•s
	Blue	R_B		4.2	6.1	8.0	V/lx•s
Image lag		IL	V_{OUT} = 1.0 V		1.5	7.0	%
Offset level **Note1**		V_{OS}		4.0	5.5	7.0	V
Output fall delay time **Note2**		t_d	V_{OUT} = 1.0 V		40		ns
Total transfer efficiency		TTE	V_{OUT} = 1.0 V, data rate = 5 MHz	92	98		%
Response peak	Red				630		nm
	Green				540		nm
	Blue				460		nm
Dynamic range		DR1	V_{sat} /DSNU		1666		times
		DR2	V_{sat} /σ		2500		times
Reset feed-through noise **Note1**		RFTN	Light shielding	–1000	–300	+500	mV
Random noise		σ	Light shielding	–	1.0	–	mV

Notes 1. Refer to **TIMING CHART 2**.

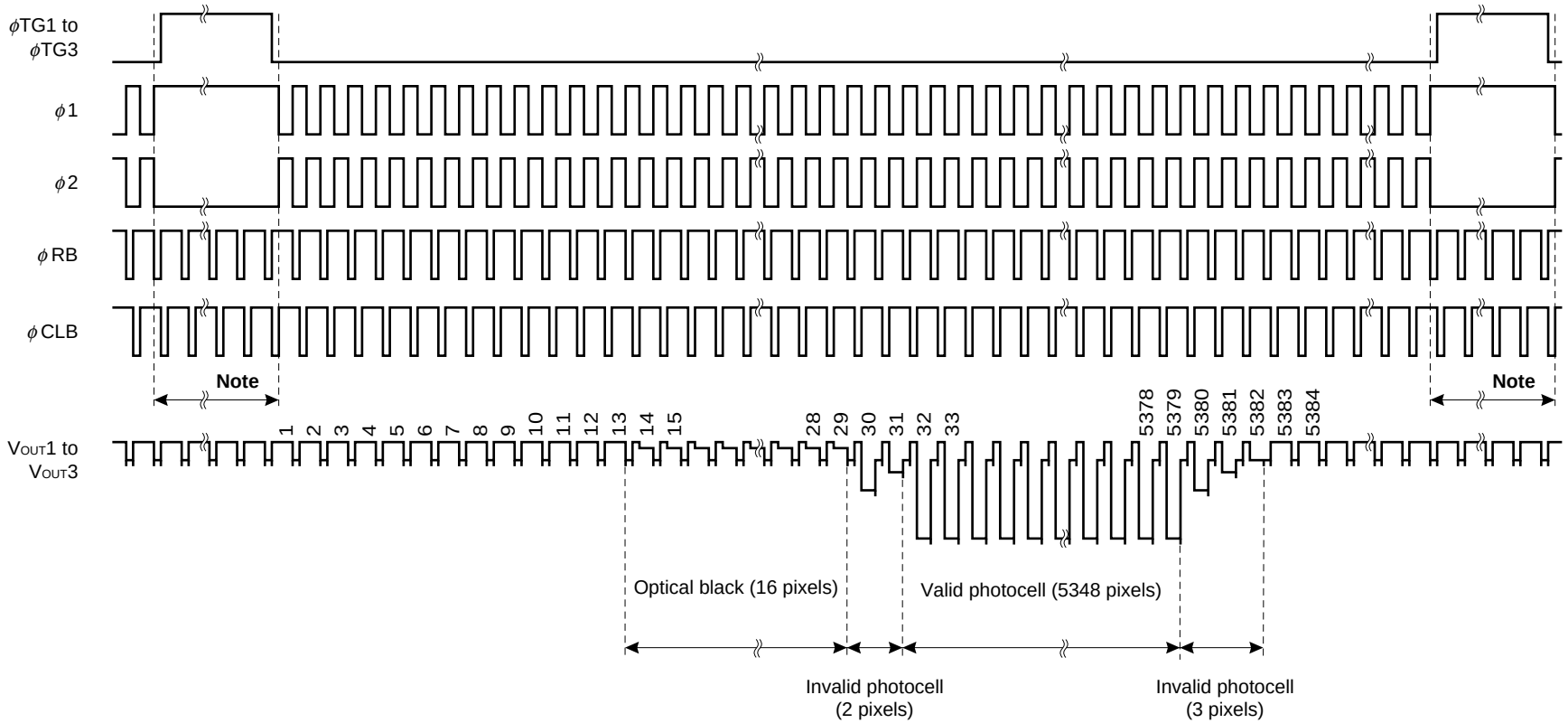
2. When the fall time of ϕ1 (t1) is the TYP. value (refer to **TIMING CHART 2**).

INPUT PIN CAPACITANCE (T_A = +25 °C, V_{OD} = 12 V)

Parameter	Symbol	Pin name	Pin No.	MIN.	TYP.	MAX.	Unit
Shift register clock pin capacitance 1	$C_{\phi 1}$	ϕ1	9		400		pF
			24		400		pF
Shift register clock pin capacitance 2	$C_{\phi 2}$	ϕ2	8		400		pF
			25		400		pF
Reset gate clock pin capacitance	$C_{\phi RB}$	ϕRB	3		15		pF
Reset feed-through level clamp clock pin capacitance	$C_{\phi CLB}$	ϕCLB	4		15		pF
Transfer gate clock pin capacitance	$C_{\phi TG}$	ϕTG1	23		100		pF
		ϕTG2	22		100		pF
		ϕTG3	10		100		pF

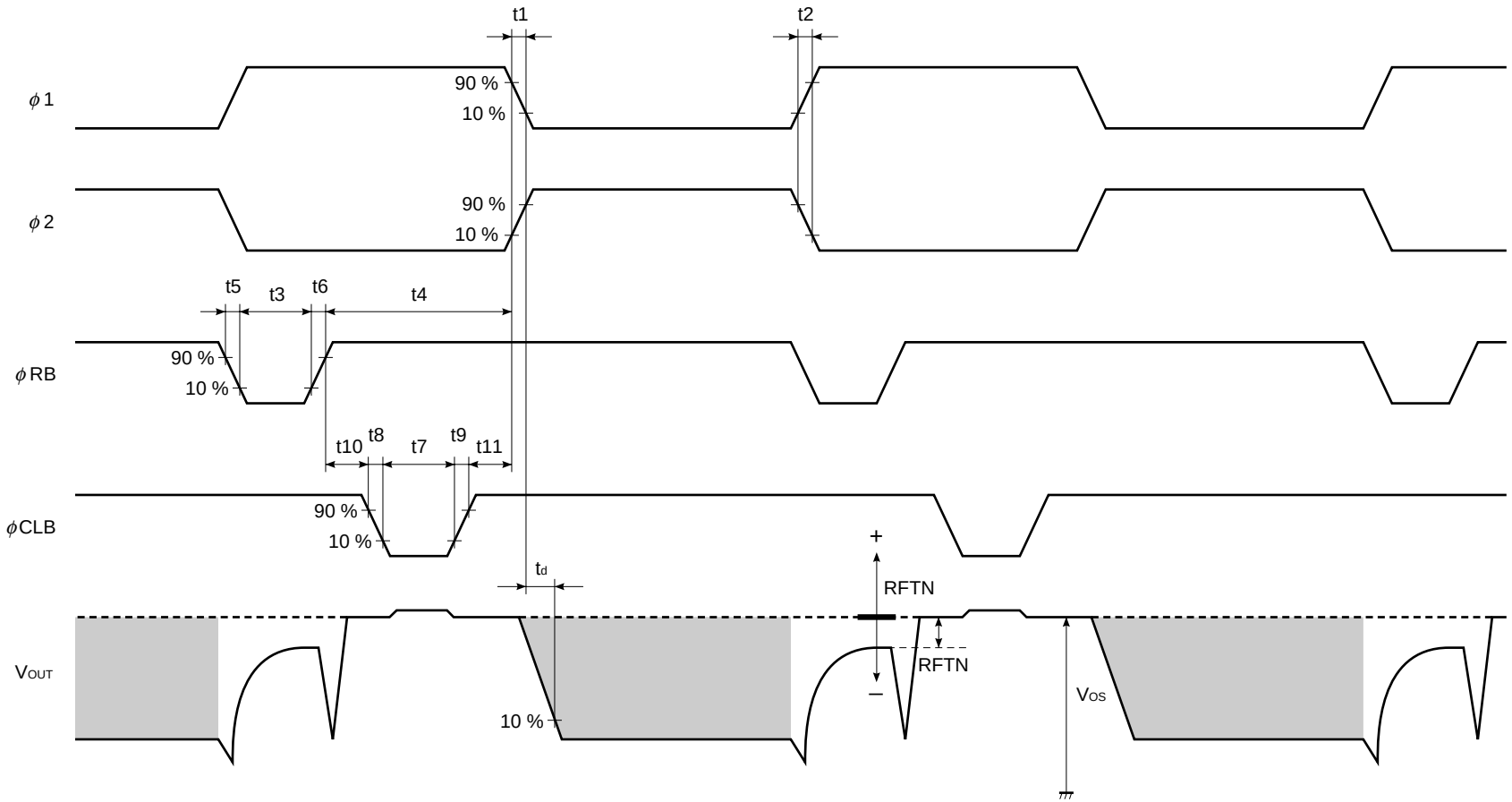
Remark Pins 9 and 24 (ϕ1), 8 and 25 (ϕ2) are each connected inside of the device.

TIMING CHART 1 (for each color)

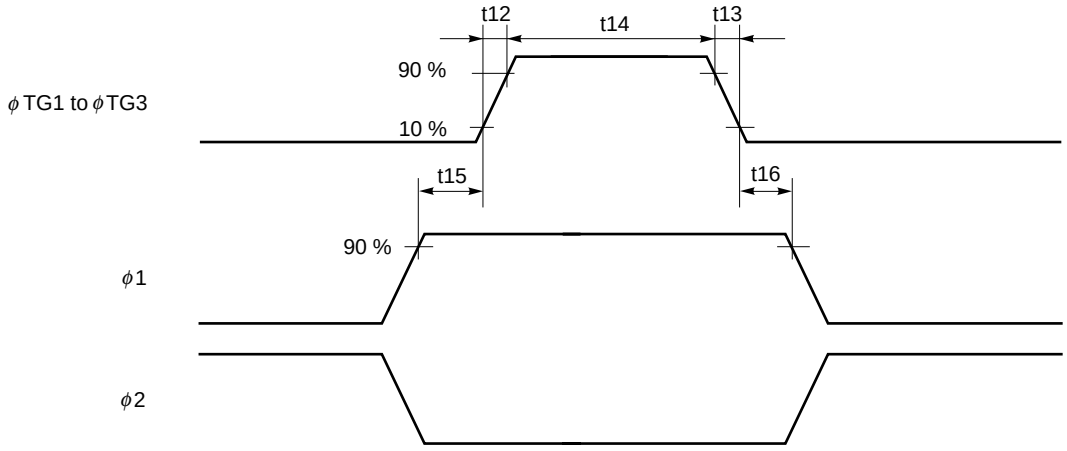


Note Input the φRB and φCLB pulses continuously during this period, too.

TIMING CHART 2 (for each color)

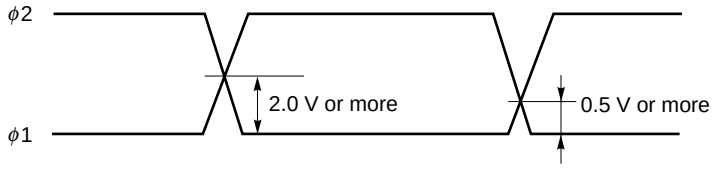


φTG1 to φTG3, φ1, φ2 TIMING CHART



Symbol	MIN.	TYP.	MAX.	Unit
t1, t2	0	25	–	ns
t3	20	50	–	ns
t4	70	250	–	ns
t5, t6	0	25	–	ns
t7	30	50	–	ns
t8, t9	0	25	–	ns
t10	30	50	–	ns
t11	5	15	–	ns
t12, t13	0	50	–	ns
t14	3000	10000	–	ns
t15, t16	900	1000	–	ns

φ1, φ2 cross points



Remark Adjust cross points of φ1 and φ2 with input resistance of each pin.

DEFINITIONS OF CHARACTERISTIC ITEMS

1. Saturation voltage: V_{sat}
   Output signal voltage at which the response linearity is lost.

2. Saturation exposure: SE
   Product of intensity of illumination (I_X) and storage time (s) when saturation of output voltage occurs.

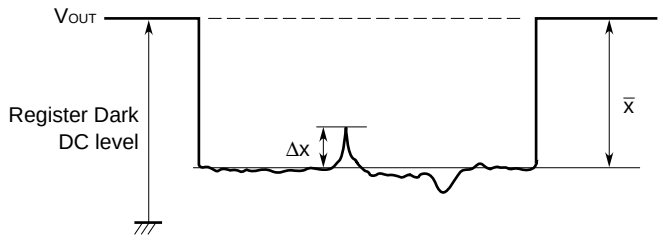
3. Photo response non-uniformity: PRNU
   The output signal non-uniformity of all the valid pixels when the photosensitive surface is applied with the light of uniform illumination. This is calculated by the following formula.

$$PRNU\ (\%) = \frac{\Delta x}{\overline{x}} \times 100$$

Δx : maximum of $|x_j - \overline{x}|$

$$\overline{x} = \frac{\sum_{j=1}^{5348} x_j}{5348}$$

x_j : Output voltage of valid pixel number j



4. Average dark signal: ADS
   Average output signal voltage of all the valid pixels at light shielding. This is calculated by the following formula.

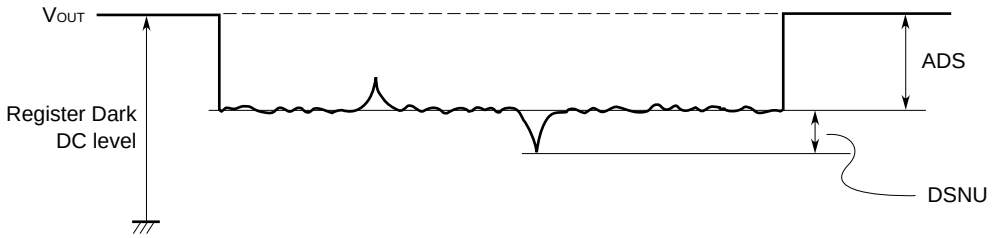
$$ADS\ (mV) = \frac{\sum_{j=1}^{5348} d_j}{5348}$$

d_j : Dark signal of valid pixel number j

5. Dark signal non-uniformity: DSNU
   Absolute maximum of the difference between ADS and voltage of the highest or lowest output pixel of all the valid pixels at light shielding. This is calculated by the following formula.

$$DSNU\ (mV) : \text{maximum of } |d_j - ADS|_{j = 1 \text{ to } 5348}$$

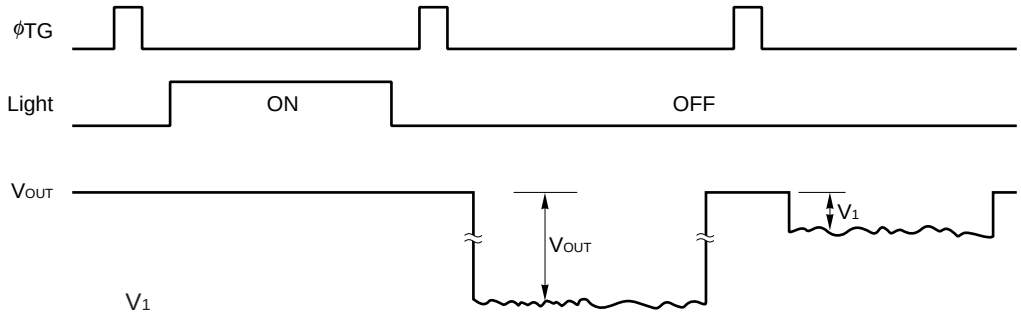
d_j : Dark signal of valid pixel number j



6. Output impedance: Z_O
   Impedance of the output pins viewed from outside.

7. Response: R
   Output voltage divided by exposure (Ix•s).
   Note that the response varies with a light source (spectral characteristic).

8. Image Lag: IL
   The rate between the last output voltage and the next one after read out the data of a line.

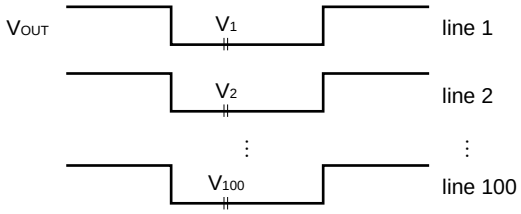


$$IL\ (\%) = \frac{V_1}{V_{OUT}} \times 100$$

9. Random noise: σ
   Random noise σ is defined as the standard deviation of a valid pixel output signal with 100 times (=100 lines) data sampling at dark (light shielding).

$$\sigma\ (mV) = \sqrt{\frac{\sum_{i=1}^{100} (V_i - \overline{V})^2}{100}} \quad , \quad \overline{V} = \frac{1}{100} \sum_{i=1}^{100} V_i$$

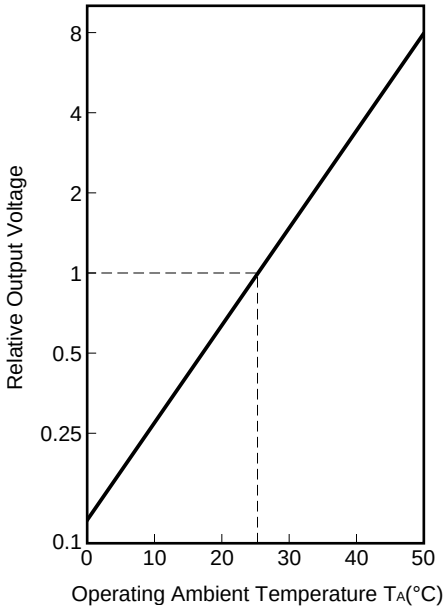
V_i: A valid pixel output signal among all of the valid pixels for each color



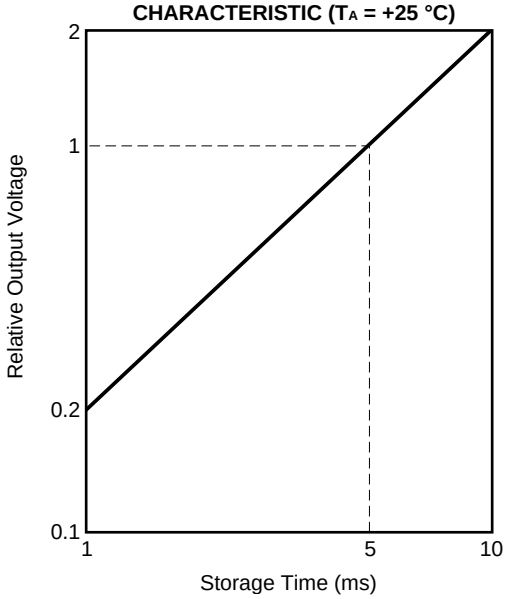
This is measured by the DC level sampling of only the signal level, not by CDS (Correlated Double Sampling).

STANDARD CHARACTERISTIC CURVES (Nominal)

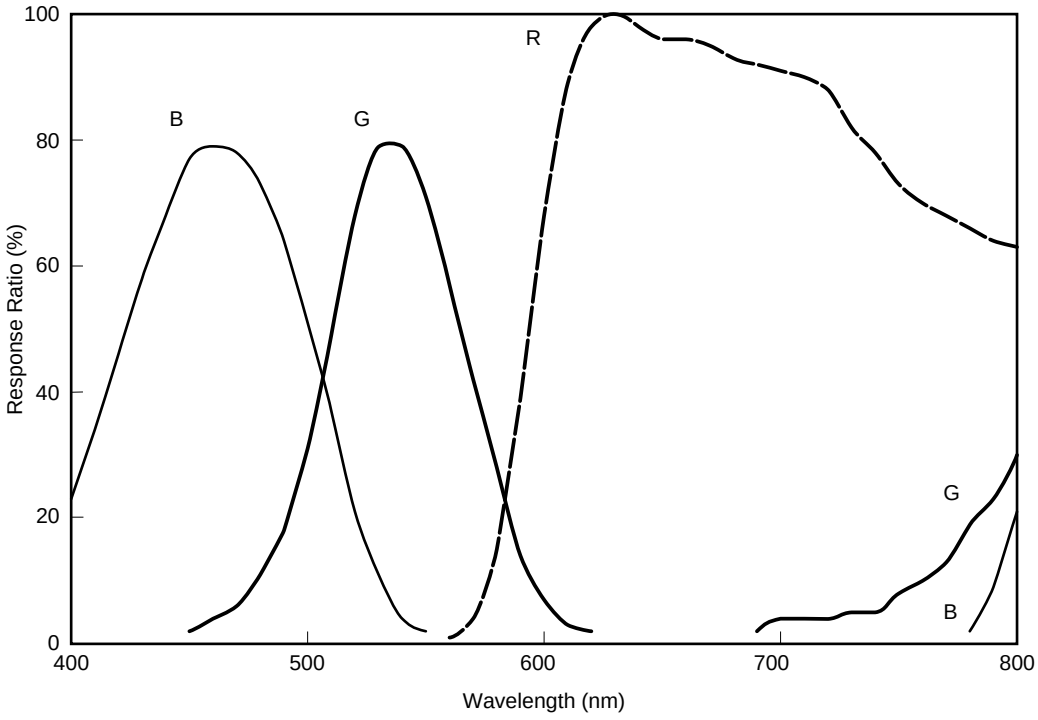
DARK OUTPUT TEMPERATURE CHARACTERISTIC



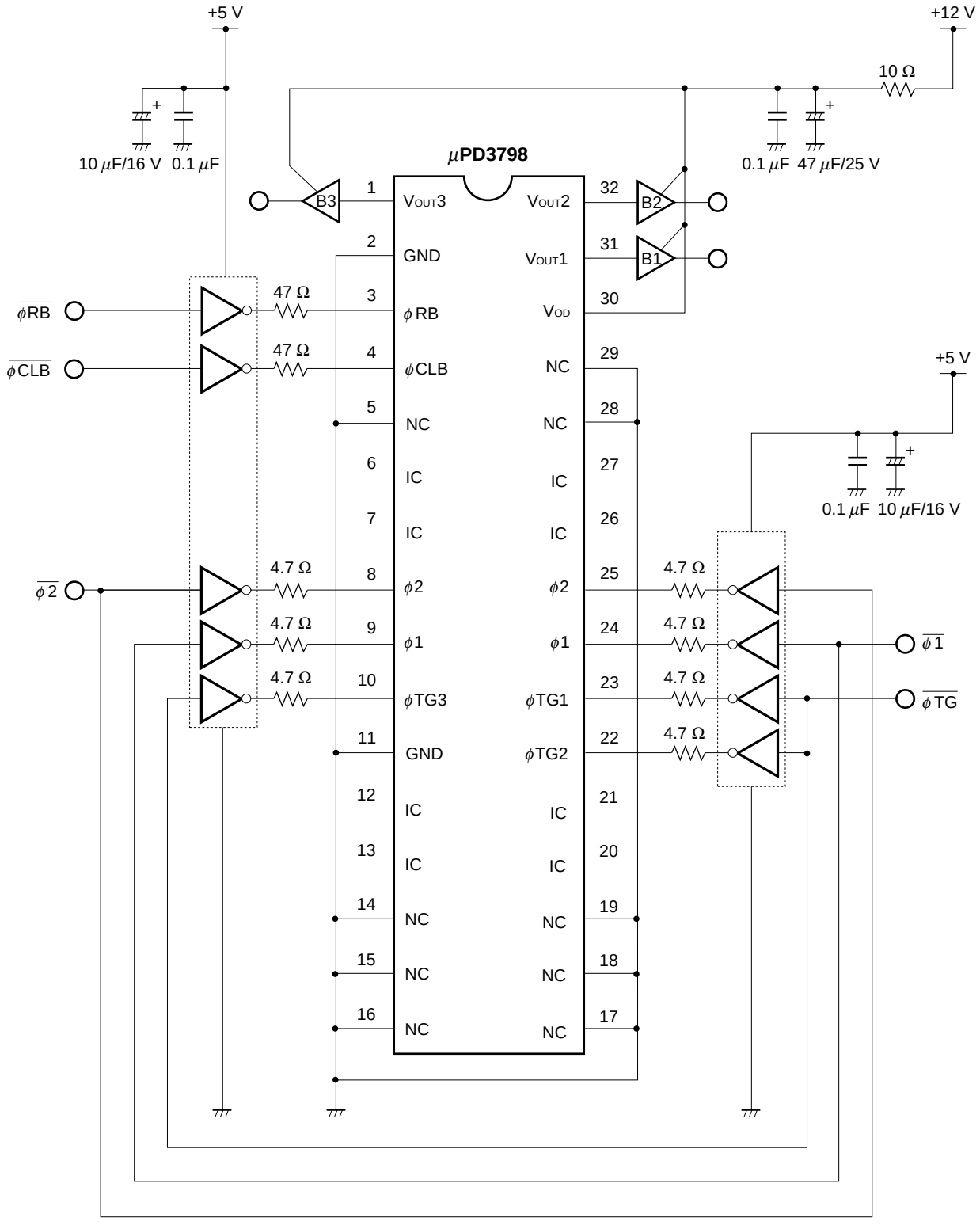
STORAGE TIME OUTPUT VOLTAGE CHARACTERISTIC (T_A = +25 °C)



TOTAL SPECTRAL RESPONSE CHARACTERISTICS (without infrared cut filter and heat absorbing filter) (T_A = +25 °C)



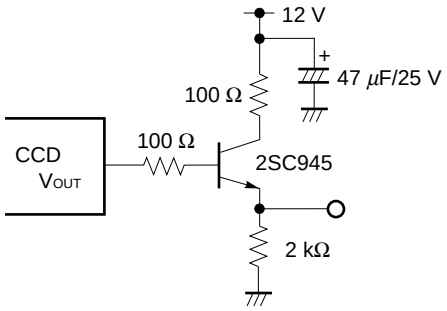
APPLICATION CIRCUIT EXAMPLE



Caution Leave pins 6, 7, 12, 13, 20, 21, 26, 27 (IC) unconnected.

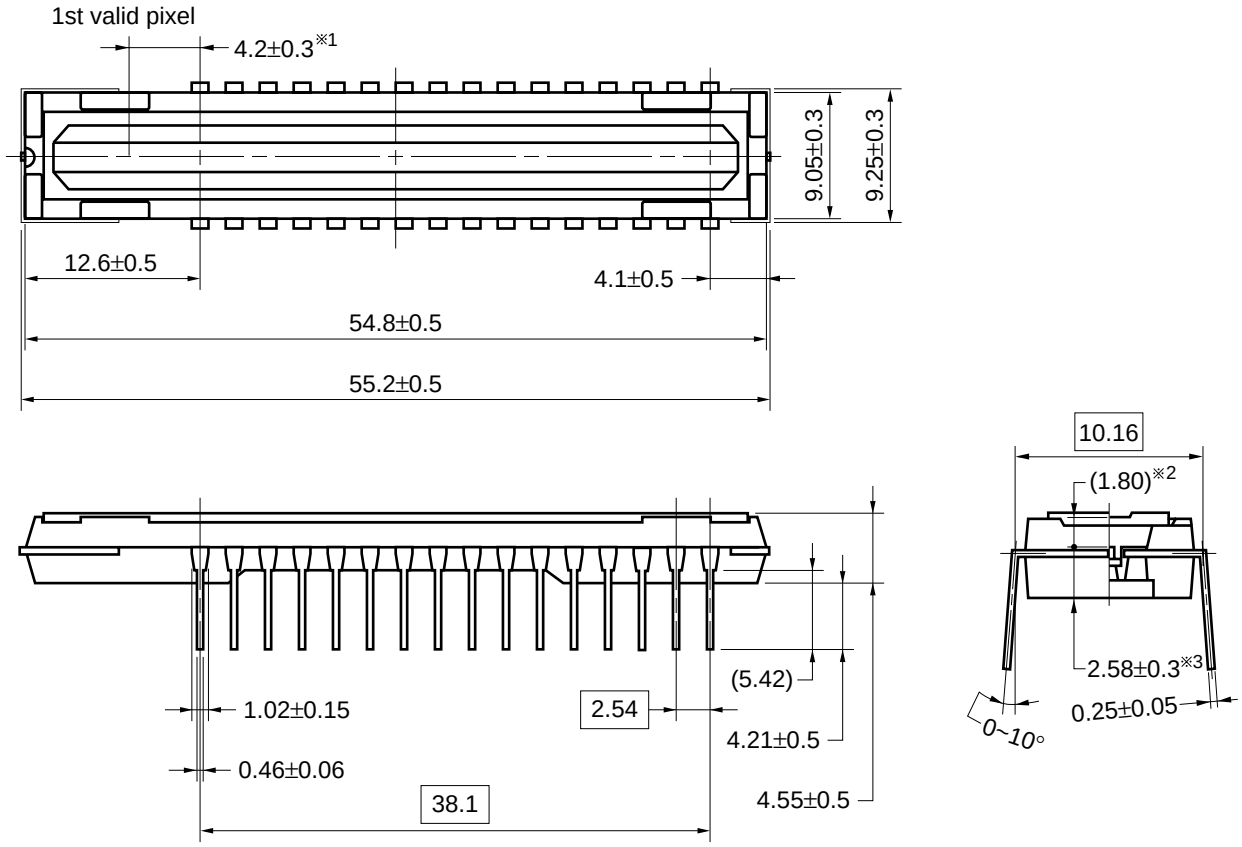
Remark The inverters shown in the above application circuit example are the 74HC04.

B1 to B3 EQUIVALENT CIRCUIT



PACKAGE DRAWING

CCD LINEAR IMAGE SENSOR 32-PIN PLASTIC DIP (400 mil)
OUTLINE DRAWINGS (Unit : mm)



Name	Dimensions	Refractive index
Plastic cap	52.2×6.4×0.7※4	1.5

※1 The 1st valid pixel ⟷ The center of the pin1

※2 The surface of the chip ⟷ The top of the cap

※3 The bottom of the package ⟷ The surface of the chip

※4 Thickness of plastic cap over CCD chip

32C-1CCD-PKG2-1

RECOMMENDED SOLDERING CONDITIONS

When soldering this product, it is highly recommended to observe the conditions as shown below.

If other soldering processes are used, or if the soldering is performed under different conditions, please make sure to consult with our sales offices.

For more details, refer to our document **"Semiconductor Device Mounting Technology Manual"(C10535E)**.

Type of Through-hole Device

μPD3798CY : CCD linear image sensor 32-pin plastic DIP (400 mil)

Process	Conditions
Partial heating method	Pin temperature: 300 °C or below, Heat time: 3 seconds or less (per pin)

Caution During assembly care should be taken to prevent solder or flux from contacting the plastic cap. The optical characteristics could be degraded by such contact.

NOTES ON CLEANING THE PLASTIC CAP

① CLEANING THE PLASTIC CAP

Care should be taken when cleaning the surface to prevent scratches.
The optical characteristics of the CCD will be degraded if the cap is scratched during cleaning.

We recommend cleaning the cap with a soft cloth moistened with one of the recommended solvents below. Excessive pressure should not be applied to the cap during cleaning. If the cap requires multiple cleanings it is recommended that a clean surface or cloth be used.

② RECOMMENDED SOLVENTS

The following are the recommended solvents for cleaning the CCD plastic cap. Use of solvents other than these could result in optical or physical degradation in the plastic cap. Please consult your sales office when considering an alternative solvent.

Solvents	Symbol
Ethyl Alcohol	EtOH
Methyl Alcohol	MeOH
Isopropyl Alcohol	IPA
N-methyl Pyrrolidone	NMP

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note:

No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note:

Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

[MEMO]

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  - Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
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